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November 2014

ISL9R860PF2 8 A, 600 V, STEALTH™ Diode

Features

- Stealth Recovery t_{rr} = 28 ns (@I_F = 8 A)
- Max Forward Voltage, V_F = 2.4 V (@ T_C = 25°C)
- 600 V Reverse Voltage and High Reliability
- · Avalanche Energy Rated
- RoHS Compliant

Applications

- · Switch Mode Power Supplies
- · Hard Switched PFC Boost Diode
- · UPS Free Wheeling Diode
- · Motor Drive FWD
- SMPS FWD
- · Snubber Diode

Description

The ISL9R860PF2 is a STEALTH™ diode optimized for low loss performance in high frequency hard switched applications. The STEALTH™ family exhibits low reverse recovery current (I_{rr}) and exceptionally soft recovery under typical operating conditions. This device is intended for use as a free wheeling or boost diode in power supplies and other power switching applications. The low I_{rr} and short ta phase reduce loss in switching transistors. The soft recovery minimizes ringing, expanding the range of conditions under which the diode may be operated without the use of additional snubber circuitry. Consider using the STEALTH™ diode with an SMPS IGBT to provide the most efficient and highest power density design at lower cost.

Package Symbol









Device Maximum Ratings T_C= 25°C unless otherwise noted

Parameter	Ratings	Unit
Peak Repetitive Reverse Voltage	600	V
Working Peak Reverse Voltage	600	V
DC Blocking Voltage	600	V
Average Rectified Forward Current (T _C = 75°C)	8	Α
Repetitive Peak Surge Current (20 kHz Square Wave)	16	Α
Nonrepetitive Peak Surge Current (Halfwave 1 Phase 60 Hz)	100	Α
Power Dissipation	26	W
Avalanche Energy (1 A, 40 mH)	20	mJ
Operating and Storage Temperature Range	-55 to 175	°C
Maximum Temperature for Soldering Leads at 0.063in (1.6mm) from Case for 10s	300	°C
	Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage Average Rectified Forward Current (T _C = 75°C) Repetitive Peak Surge Current (20 kHz Square Wave) Nonrepetitive Peak Surge Current (Halfwave 1 Phase 60 Hz) Power Dissipation Avalanche Energy (1 A, 40 mH) Operating and Storage Temperature Range Maximum Temperature for Soldering	Peak Repetitive Reverse Voltage 600 Working Peak Reverse Voltage 600 DC Blocking Voltage 600 Average Rectified Forward Current (T _C = 75°C) 8 Repetitive Peak Surge Current (20 kHz Square Wave) 16 Nonrepetitive Peak Surge Current (Halfwave 1 Phase 60 Hz) 100 Power Dissipation 26 Avalanche Energy (1 A, 40 mH) 20 Operating and Storage Temperature Range -55 to 175 Maximum Temperature for Soldering

CAUTION: Stresses above those listed in "Device Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

Part Num	ber	Top Mark	Package	Packing Method	Reel Size	Tape	Width	Qι	Quantity	
ISL9R860F	PF2	ISL9R860PF2	TO-220F-2L	Tube	N/A	N/A			50	
Electric	cal (Characteris	Stics T _C = 25°C	unless otherwise no	oted					
Symbol			Test Conditions		Min	Тур	Max	Unit		
Off State	Cha	aracteristics							•	
		antaneous Revers	se Current	V _R = 600 V	T _C = 25°C	-	-	100	μА	
				11	T _C = 125°C	-	-	1.0	mA	
On State	Cha	aracteristics			•	•				
		Instantaneous Forward Voltage		I _F = 8 A	T _C = 25°C	_	2.0	2.4	V	
٧F	111316	antaneous i oiwa	id voltage	IF = 0 A	$T_{\rm C} = 25^{\circ}{\rm C}$	_	1.6	2.0	V	
	4.				1.0 .200					
Dynamic	Cha	aracteristics								
CJ	Junc	tion Capacitance		$V_R = 10 \text{ V}, I_F = 0 \text{ A}$		-	30	-	pF	
Switchin	ıg Ch	naracteristics	.							
t _{rr}	Reverse Recovery Time		$I_F = 1 \text{ A}, di_F/dt = 10$	$00 \text{ A/}\mu\text{s}, V_{R} = 30 \text{ V}$	-	18	25	ns		
		$I_F = 8 \text{ A}, di_F/dt = 100 \text{ A/}\mu\text{s}, V_R = 30 \text{ V}$		-	21	30	ns			
t _{rr}	Reverse Recovery Time			I _F = 8 A,		-	28	-	ns	
I _{rr}	Maximum Reverse Recovery Current		$di_F/dt = 200 \text{ A/}\mu\text{s},$ $V_R = 390 \text{ V}, T_C = 25^{\circ}\text{C}$		-	3.2	-	Α		
Q _{rr}	Reverse Recovery Charge				-	50	-	nC		
t _{rr}	Reverse Recovery Time			I _F = 8 A,		- \	77	-	ns	
S	Softness Factor (t _b /t _a)		$di_F/dt = 200 A/\mu s$		-	3.7	-			
	Maximum Reverse Recovery Current		$V_{R} = 390 \text{ V},$		-	3.4	-	Α		
Q _{rr}	Reverse Recovery Charge		$T_C = 125^{\circ}C$		-	150	-	nC		
t _{rr}	Reve	Reverse Recovery Time		I _F = 8 A,		-	53	-	ns	
S	Softness Factor (t _b /t _a)		$di_F/dt = 600 A/\mu s$,		-	2.5	-			
Irr	Maximum Reverse Recovery Current Reverse Recovery Charge		∇ _R = 390 V, - T _C = 125°C		-	6.5	-	Α		
Q _{rr}						195	-	nC		
dl _M /dt	Maximum di/dt during t _b				- /	500	-	A/µs		
Thermal	Cha	racteristics								
	Thermal Resistance Junction to Case								1	
$R_{\theta JC}$	Ther	mal Resistance	Junction to Case			/ -	-	4.8	°C/W	

Typical Performance Curves 16 14 12 FORWARD CURRENT (A) 10 8 6 2 0.25 0.5 0.75 1 1.25 1.5 1.75 V_F, FORWARD VOLTAGE (V) Figure 1. Forward Current vs Forward Voltage $V_R = 390V, T_J = 125^{\circ}C$ 70 t_b AT $d_F/dt = 200A/\mu s$, $500A/\mu s$, $800A/\mu s$ 60 50

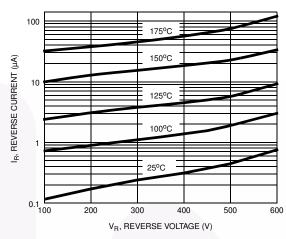
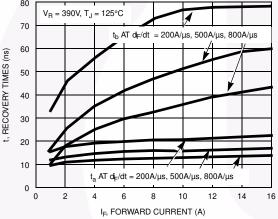


Figure 2. Reverse Current vs Reverse Voltage



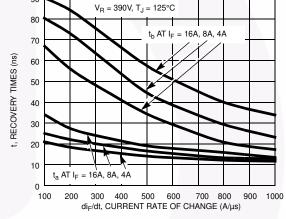
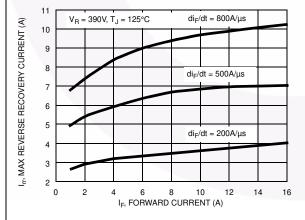


Figure 3. t_a and t_b Curves vs Forward Current

Figure 4. t_a and t_b Curves vs di_F/dt



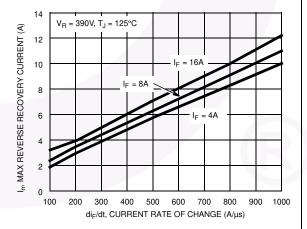
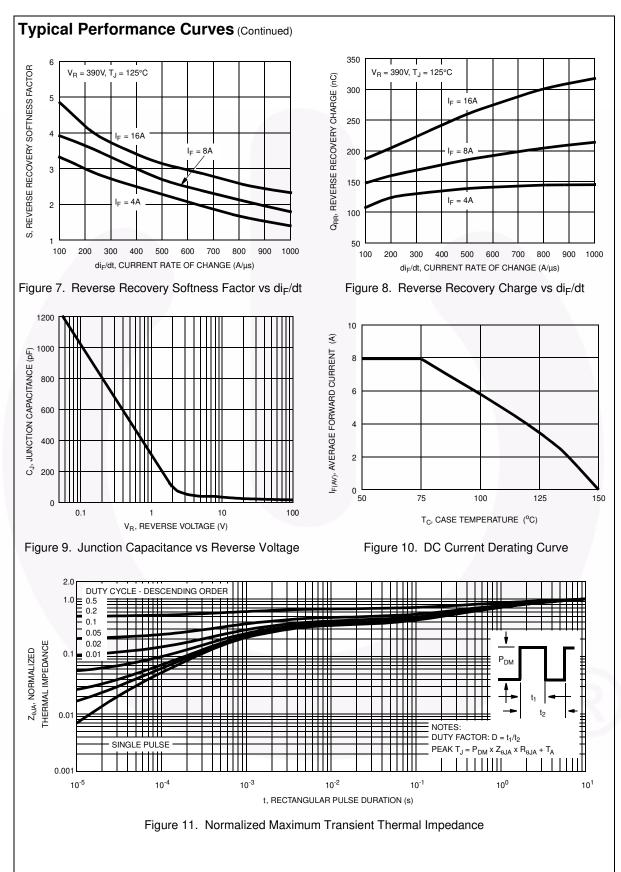
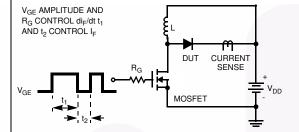


Figure 5. Maximum Reverse Recovery Current vs Forward Current

Figure 6. Maximum Reverse Recovery Current vs di_{F}/dt



Test Circuits and Waveforms



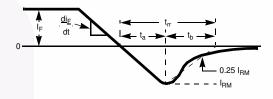
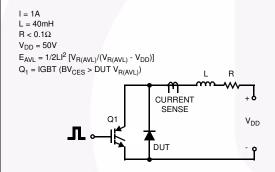


Figure 12. t_{rr} Test Circuit

Figure 13. t_{rr} Waveforms and Definitions



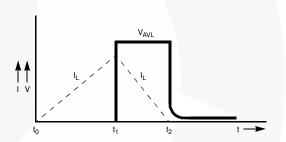


Figure 14. Avalanche Energy Test Circuit

Figure 15. Avalanche Current and Voltage Waveforms

Mechanical Dimensions

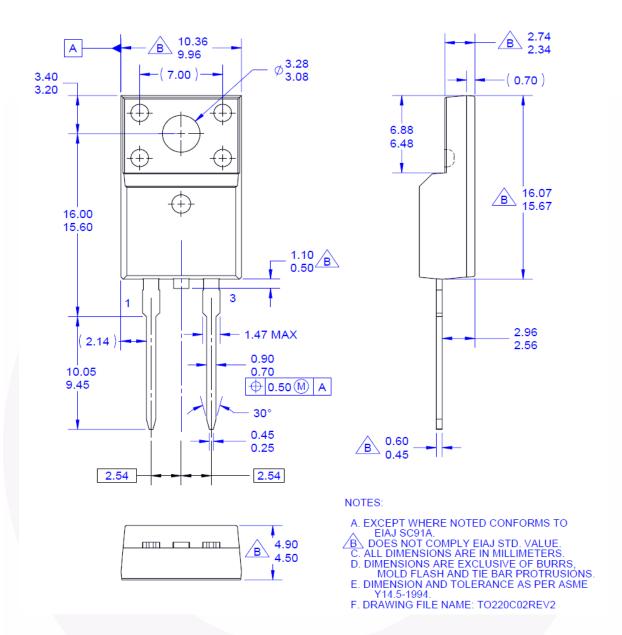


Figure 16. TO-220F 2L - 2LD; TO220; MOLDED; FULL PACK

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